

TECHNICAL DATA SHEET 2/6	
MALE STRAIGHT RECEPTA	CLE R222.508.722
SMT TYPE - CATCHER'S MI	TT Series : SMP
PACKAGINGStandardUnit500'W' optionContact us	<u>SPECIFICATION</u>
ELECTRICAL CHARACTERISTICS	ENVIRONMENTAL
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	Maxi
Dielectric withstanding voltage500Veff miniInsulation resistance5000MΩ mini	OTHER CHARACTERISTICS
MECHANICAL CHARACTERISTICS Center contact retention Axial force – Mating end 6.8 N mini Axial force – Opposite end NA N mini Torque NA N.cm mini Recommended torque NA N.cm Mating NA N.cm Mating life 1000 Cycles mini	Assembly instruction Others : Compliant with MIL-STD-348 *At 12.4Ghz - Performance strongly depends on lay out and pcb material
Weight 0,4600 g Issue : 0939 B In the effort to improve our products, we reserve the right to make changes judged to be RADIALLES	

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MALE STRAIGHT RECEPTACLE

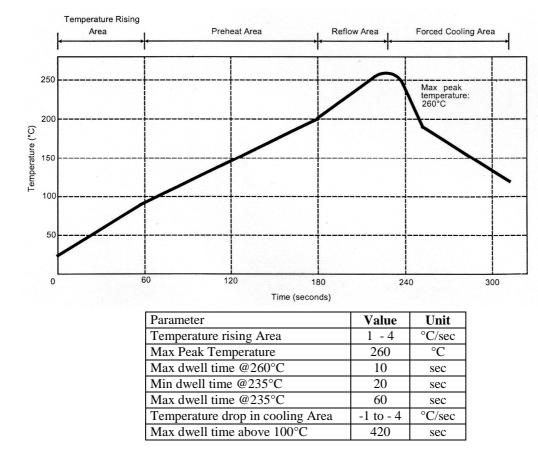
SMT TYPE - CATCHER'S MITT

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SOLDER PROCEDURE

- Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 μm. Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
 Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- Soldering by infra-red reflow.
 Below, please find the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.



TEMPERATURE PROFILE

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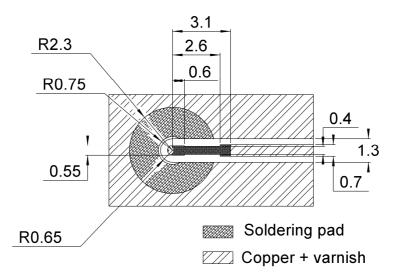
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RECOMMENDED PAD DIMENSIONS:

Substrate: RT5880 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise



Substrate: RO4350 thickness 0.254mm, with copper layer 35µm on both sides: Add vias between both sides along upper ground plane according to engineering practise

